







	10	9	8	1	7	6	5	4	3	2	1	/
F	,			,				,				F
E		PART NO.	VOLTAGE KEY	DIM 'P'	DIM 'Q'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING	SOLDERTAIL PLATING	LUBF	RICATION		E
D		87803-0002 87803-0022 87803-0012 87803-0032 87803-0052 87803-0062	1.8V	2.79 3.18 4.00	3.18	1.57 2.36 3.18	0.38uM/ 15u" GOLD OVER 1.27uM/ 50u" MIN NICKEL	_2.54uM/ 100u" MIN. TIN (MATTE) OVER 1.27uM/ 50u" MIN NICKEL	,	NO YES NO YES NO YES		D
C		87803-0102 87803-0122 87803-0112 87803-0132 87803-0152		2.79 3.18	3.18	1.57 2.36 3.18	0.76uM/ 30u" GOLD OVER 1.27uM/ 50u" MIN NICKEL		KEL	NO YES NO YES NO		С
В		87803-0162								ÆS		В
					D OPTION	CHKD:CGTAN 2009/03/27 CHKD:CGTAN 2009/03/27 APPR:SHLENI 2009/03/27 OESCRIPTION OF CHKD:CGTAN 2009/03/27 OF CHKD:CGTAN 20	GENERAL TOLERANCE (UNLESS SPECIFIED) Mm INC 4 PLACES ± ± 3 PLACES ± ± 2 PLACES ± 0.25 ± 1 PLACE ± ± ANGULAR ± 5 °	MM ONLY	/26 /26 molex	240 CK MOLEX II	○ □ PRÖJEĆ 1, 1.00MM PITCH TS, 25 DEG. NCORPORATE	H A
	b_frame_A3_P_AM_T lev. E 2006/04/15	9	8		7	BT APPRISE	DRAFT WHERE APPLICA MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.	DOCUMENT N	SD-87803	3-010 5	SHEET NO. 5 OF 5 MOLEX RMISSION